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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	696
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgxea7k3f40c2n">https://www.e-xfl.com/product-detail/intel/5sgxea7k3f40c2n</a>

Table 8 shows the transceiver power supply voltage requirements for various conditions.

**Table 8. Transceiver Power Supply Voltage Requirements**

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB <sup>(2)</sup>	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true: <ul style="list-style-type: none"> <li>■ Data rate &gt; 10.3 Gbps.</li> <li>■ DFE is used.</li> </ul>	All	1.05	3.0	1.5	V
If ANY of the following conditions are true <sup>(1)</sup> : <ul style="list-style-type: none"> <li>■ ATX PLL is used.</li> <li>■ Data rate &gt; 6.5Gbps.</li> <li>■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.</li> </ul>	All	1.0			
If ALL of the following conditions are true: <ul style="list-style-type: none"> <li>■ ATX PLL is not used.</li> <li>■ Data rate ≤ 6.5Gbps.</li> <li>■ DFE, AEQ, and EyeQ are not used.</li> </ul>	C1, C2, I2, and I3YY	0.90	2.5		
	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		

**Notes to Table 8:**

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR\_GXB and VCCT\_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR\_GXB and VCCT\_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

## DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

### I/O Pin Leakage Current

Table 9 lists the Stratix V I/O pin leakage current specifications.

**Table 9. I/O Pin Leakage Current for Stratix V Devices <sup>(1)</sup>**

Symbol	Description	Conditions	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0 \text{ V to } V_{CCIO\text{MAX}}$	-30	—	30	$\mu\text{A}$

**Note to Table 9:**

(1) If  $V_O = V_{CCIO}$  to  $V_{CCIO\text{MAX}}$ , 100  $\mu\text{A}$  of leakage current per I/O is expected.

### Bus Hold Specifications

Table 10 lists the Stratix V device family bus hold specifications.

**Table 10. Bus Hold Parameters for Stratix V Devices**

Parameter	Symbol	Conditions	V <sub>CCIO</sub>										Unit
			1.2 V		1.5 V		1.8 V		2.5 V		3.0 V		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Low sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (maximum)	22.5	—	25.0	—	30.0	—	50.0	—	70.0	—	μA
High sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (minimum)	−22.5	—	−25.0	—	−30.0	—	−50.0	—	−70.0	—	μA
Low overdrive current	I <sub>ODL</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	120	—	160	—	200	—	300	—	500	μA
High overdrive current	I <sub>ODH</sub>	0V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−120	—	−160	—	−200	—	−300	—	−500	μA
Bus-hold trip point	V <sub>TRIP</sub>	—	0.45	0.95	0.50	1.00	0.68	1.07	0.70	1.70	0.80	2.00	V

### On-Chip Termination (OCT) Specifications

If you enable OCT calibration, calibration is automatically performed at power-up for I/Os connected to the calibration block. Table 11 lists the Stratix V OCT termination calibration accuracy specifications.

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices <sup>(1)</sup> (Part 1 of 2)**

Symbol	Description	Conditions	Calibration Accuracy				Unit
			C1	C2,I2	C3,I3, I3YY	C4,I4	
25- $\Omega$ $R_S$	Internal series termination with calibration (25- $\Omega$ setting)	$V_{\text{CCIO}} = 3.0, 2.5, 1.8, 1.5, 1.2 \text{ V}$	$\pm 15$	$\pm 15$	$\pm 15$	$\pm 15$	%

- 
-  You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.
-  For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 3 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Reconfiguration clock ( <code>mgmt_clk_clk</code> ) frequency	—	100	—	125	100	—	125	100	—	125	MHz
<b>Receiver</b>											
Supported I/O Standards	—	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Data rate (Standard PCS) (9), (23)	—	600	—	12200	600	—	12200	600	—	8500/ 10312.5 (24)	Mbps
Data rate (10G PCS) (9), (23)	—	600	—	14100	600	—	12500	600	—	8500/ 10312.5 (24)	Mbps
Absolute $V_{MAX}$ for a receiver pin <sup>(5)</sup>	—	—	—	1.2	—	—	1.2	—	—	1.2	V
Absolute $V_{MIN}$ for a receiver pin	—	−0.4	—	—	−0.4	—	—	−0.4	—	—	V
Maximum peak- to-peak differential input voltage $V_{ID}$ (diff p- p) before device configuration <sup>(22)</sup>	—	—	—	1.6	—	—	1.6	—	—	1.6	V
Maximum peak- to-peak differential input voltage $V_{ID}$ (diff p- p) after device configuration <sup>(18)</sup> , (22)	$V_{CCR\_GXB} =$ 1.0 V/1.05 V ( $V_{ICM} =$ 0.70 V)	—	—	2.0	—	—	2.0	—	—	2.0	V
	$V_{CCR\_GXB} =$ 0.90 V ( $V_{ICM} = 0.6$ V)	—	—	2.4	—	—	2.4	—	—	2.4	V
	$V_{CCR\_GXB} =$ 0.85 V ( $V_{ICM} = 0.6$ V)	—	—	2.4	—	—	2.4	—	—	2.4	V
Minimum differential eye opening at receiver serial input pins <sup>(6)</sup> , (22), (27)	—	85	—	—	85	—	—	85	—	—	mV

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 7 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$t_{pll\_lock}^{(16)}$	—	—	—	10	—	—	10	—	—	10	μs

**Notes to Table 23:**

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the  $V_{CCR\_GXB}$  power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows  $V_{CCR\_GXB}$ .
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11)  $t_{LTR}$  is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12)  $t_{LTD}$  is time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high.
- (13)  $t_{LTD\_manual}$  is the time required for the receiver CDR to start recovering valid data after the rx\_is\_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14)  $t_{LTR\_LTD\_manual}$  is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx\_is\_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15)  $t_{pll\_powerdown}$  is the PLL powerdown minimum pulse width.
- (16)  $t_{pll\_lock}$  is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz  $\times$  100/f.
- (18) The maximum peak to peak differential input voltage  $V_{ID}$  after device configuration is equal to  $4 \times (\text{absolute } V_{MAX} \text{ for receiver pin} - V_{ICM})$ .
- (19) For ES devices,  $R_{REF}$  is  $2000 \Omega \pm 1\%$ .
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz +  $20 \times \log(f/622)$ .
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with  $100 \Omega$ . The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Reference Clock								
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LVDS, and HCSL						
	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS						
Input Reference Clock Frequency (CMU PLL) <sup>(6)</sup>	—	40	—	710	40	—	710	MHz
Input Reference Clock Frequency (ATX PLL) <sup>(6)</sup>	—	100	—	710	100	—	710	MHz
Rise time	20% to 80%	—	—	400	—	—	400	ps
Fall time	80% to 20%	—	—	400	—	—	400	
Duty cycle	—	45	—	55	45	—	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	—	33	30	—	33	kHz
Spread-spectrum downspread	PCIe	—	0 to −0.5	—	—	0 to −0.5	—	%
On-chip termination resistors <sup>(19)</sup>	—	—	100	—	—	100	—	Ω
Absolute V <sub>MAX</sub> <sup>(3)</sup>	Dedicated reference clock pin	—	—	1.6	—	—	1.6	V
	RX reference clock pin	—	—	1.2	—	—	1.2	
Absolute V <sub>MIN</sub>	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	mV
V <sub>ICM</sub> (AC coupled)	Dedicated reference clock pin	1050/1000 <sup>(2)</sup>			1050/1000 <sup>(2)</sup>			mV
	RX reference clock pin	1.0/0.9/0.85 <sup>(22)</sup>			1.0/0.9/0.85 <sup>(22)</sup>			V
V <sub>ICM</sub> (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	mV

Figure 4 shows the differential transmitter output waveform.

**Figure 4. Differential Transmitter/Receiver Output/Input Waveform**

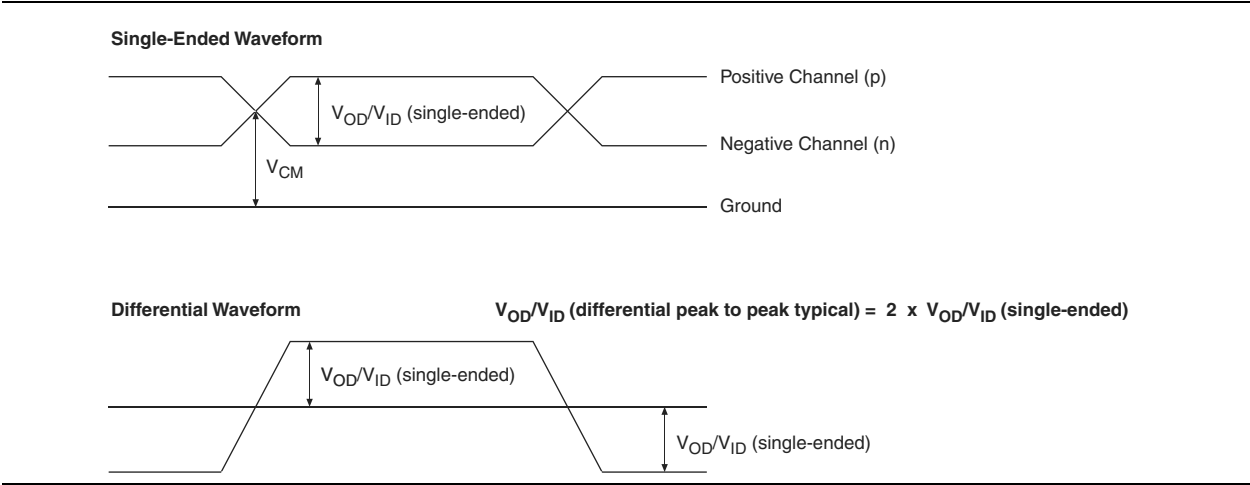


Figure 5 shows the Stratix V AC gain curves for GT channels.

**Figure 5. AC Gain Curves for GT Channels**



**Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)**

Mode	Peformance							Unit
	C1	C2, C2L	I2, I2L	C3	I3, I3L, I3YY	C4	I4	
Modes using Three DSPs								
One complex 18 x 25	425	425	415	340	340	275	265	MHz
Modes using Four DSPs								
One complex 27 x 27	465	465	465	380	380	300	290	MHz

### Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

**Table 33. Memory Block Performance Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 2)**

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
MLAB	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x16 depth <sup>(3)</sup>	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

**Table 33. Memory Block Performance Specifications for Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
M20K Block	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to <b>Old Data</b> , all supported widths	0	1	525	525	455	400	525	455	400	MHz
	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

**Notes to Table 33:**

- (1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.
- (2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in  $F_{MAX}$ .
- (3) The  $F_{MAX}$  specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

**Temperature Sensing Diode Specifications**

Table 34 lists the internal TSD specification.

**Table 34. Internal Temperature Sensing Diode Specification**

Temperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
–40°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

**Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices**

Description	Min	Typ	Max	Unit
$I_{bias}$ , diode source current	8	—	200	μA
$V_{bias}$ , voltage across diode	0.3	—	0.9	V
Series resistance	—	—	< 1	Ω
Diode ideality factor	1.006	1.008	1.010	—

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

**Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled**

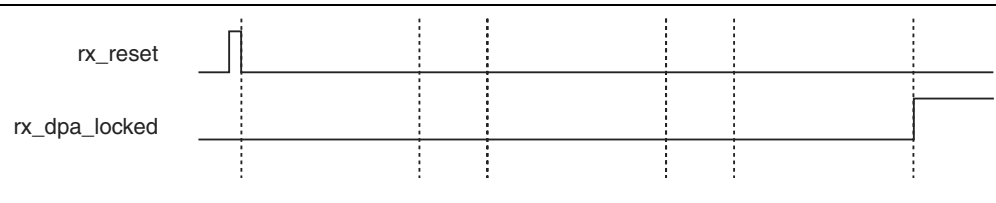


Table 37 lists the DPA lock time specifications for Stratix V devices.

**Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only <sup>(1), (2), (3)</sup>**

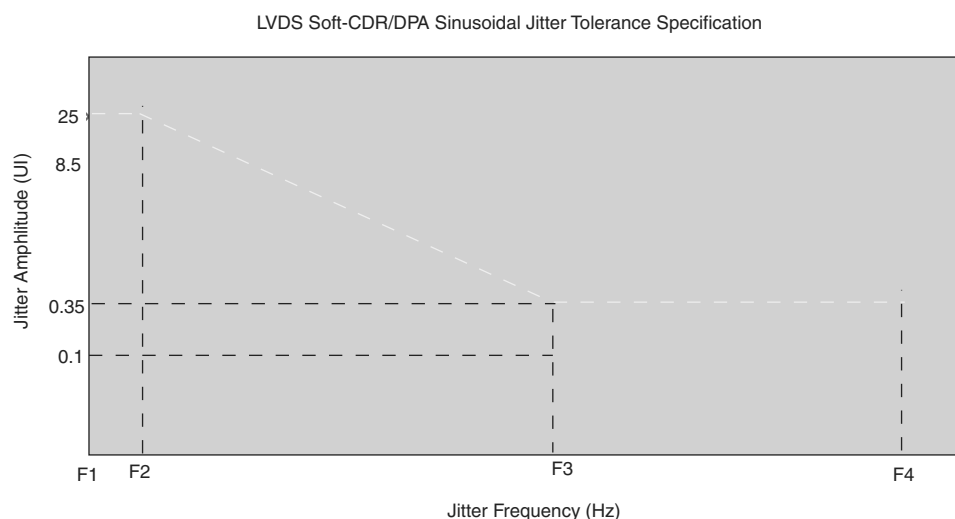
Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions <sup>(4)</sup>	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

**Notes to Table 37:**

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the LVDS soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps. Table 38 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps.

**Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $\geq 1.25$  Gbps**



## Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

**Table 44. Worst-Case DCD on Stratix V I/O Pins <sup>(1)</sup>**

Symbol	C1		C2, C2L, I2, I2L		C3, I3, I3L, I3YY		C4, I4		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

**Note to Table 44:**

(1) The DCD numbers do not cover the core clock network.

## Configuration Specification

### POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

**Table 45. Fast and Standard POR Delay Specification <sup>(1)</sup>**

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

**Note to Table 45:**

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

### JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

**Table 46. JTAG Timing Parameters and Values for Stratix V Devices**

Symbol	Description	Min	Max	Unit
t <sub>JCP</sub>	TCK clock period <sup>(2)</sup>	30	—	ns
t <sub>JCP</sub>	TCK clock period <sup>(2)</sup>	167	—	ns
t <sub>JCH</sub>	TCK clock high time <sup>(2)</sup>	14	—	ns
t <sub>JCL</sub>	TCK clock low time <sup>(2)</sup>	14	—	ns
t <sub>JPSU (TDI)</sub>	TDI JTAG port setup time	2	—	ns
t <sub>JPSU (TMS)</sub>	TMS JTAG port setup time	3	—	ns

**Table 47. Uncompressed .rbf Sizes for Stratix V Devices**

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) <sup>(4), (5)</sup>
Stratix V E <sup>(1)</sup>	5SEE9	—	342,742,976	700,888
	5SEEB	—	342,742,976	700,888

**Notes to Table 47:**

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.tff) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.



For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices*. For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

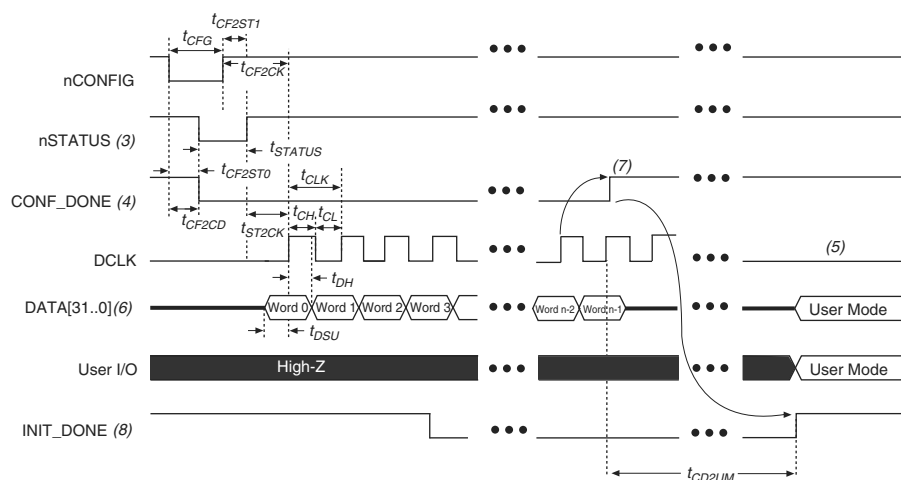
**Table 48. Minimum Configuration Time Estimation for Stratix V Devices**

Variant	Member Code	Active Serial <sup>(1)</sup>			Fast Passive Parallel <sup>(2)</sup>		
		Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
GX	A3	4	100	0.534	32	100	0.067
		4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	B9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
	C7	4	100	0.675	32	100	0.084

## FPP Configuration Timing when DCLK-to-DATA [] = 1

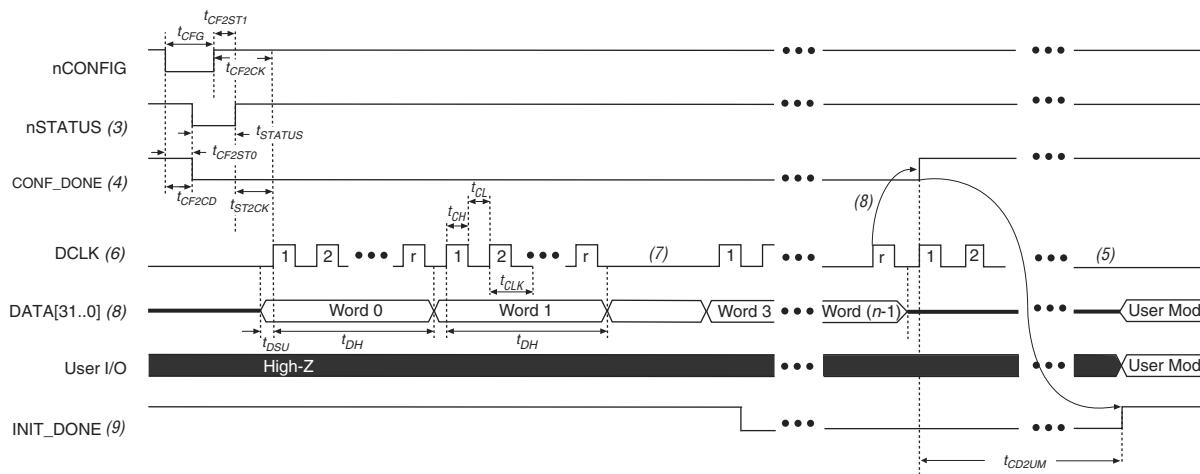
Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is 1.

**Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 <sup>(1), (2)</sup>**



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP  $\times 16$ , use DATA [15..0]. For FPP  $\times 8$ , use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)****Notes to Figure 13:**

- (1) Use this timing waveform and parameters when the DCLK-to-DATA[] ratio is >1. To find out the DCLK-to-DATA[] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA[31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 2 of 2)**

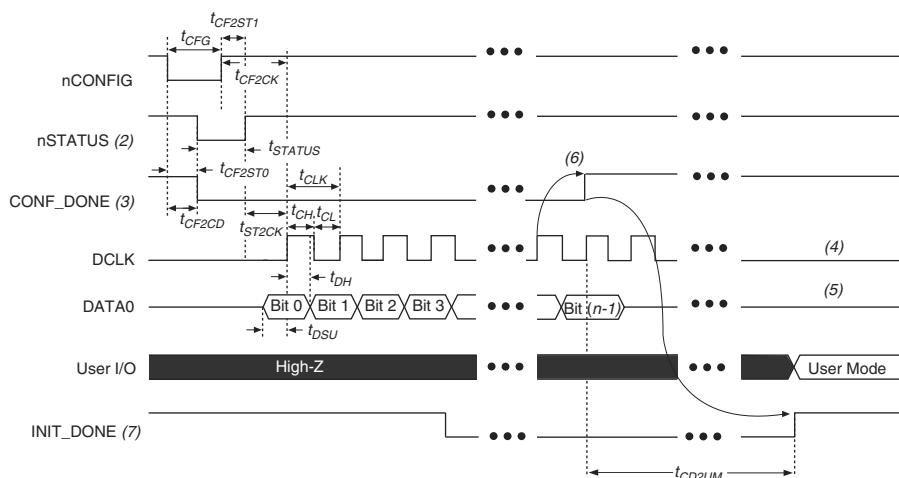
Symbol	Parameter	Minimum	Maximum	Units
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	μs
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$	—	—

**Notes to Table 53:**

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (2)  $t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63.
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

**Figure 15. PS Configuration Timing Waveform <sup>(1)</sup>****Notes to Figure 15:**

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF\_DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.



Table 54 lists the PS configuration timing parameters for Stratix V devices.

**Table 54. PS Timing Parameters for Stratix V Devices**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1,506 <sup>(1)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1,506 <sup>(2)</sup>	$\mu$ s
$t_{CF2CK}$ <sup>(5)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	$\mu$ s
$t_{ST2CK}$ <sup>(5)</sup>	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA [] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA [] hold time after rising edge on DCLK	0	—	ns
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	s
$f_{MAX}$	DCLK frequency	—	125	MHz
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(3)</sup>	175	437	$\mu$ s
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ <sup>(4)</sup>	—	—

**Notes to Table 54:**

- (1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.
- (3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section.
- (5) If nSTATUS is monitored, follow the  $t_{ST2CK}$  specification. If nSTATUS is not monitored, follow the  $t_{CF2CK}$  specification.

## Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

**Table 55. Initialization Clock Source Option and the Maximum Frequency**

Initialization Clock Source	Configuration Schemes	Maximum Frequency	Minimum Number of Clock Cycles <sup>(1)</sup>
Internal Oscillator	AS, PS, FPP	12.5 MHz	8576
CLKUSR	AS, PS, FPP <sup>(2)</sup>	125 MHz	
DCLK	PS, FPP	125 MHz	

**Notes to Table 55:**

- (1) The minimum number of clock cycles required for device initialization.
- (2) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

Table 60. Glossary (Part 3 of 4)

Letter	Subject	Definitions
S	SW (sampling window)	<p>Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:</p> 
	Single-ended voltage referenced I/O standard	<p>The JEDEC standard for <b>SSTL</b> and <b>HSTL</b> I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:</p> <p><i>Single-Ended Voltage Referenced I/O Standard</i></p> 
T	$t_c$	High-speed receiver and transmitter input and output clock period.
	TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including $t_{CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the <i>Timing Diagram</i> figure under <b>SW</b> in this table).
	$t_{DUTY}$	<p>High-speed I/O block—Duty cycle on the high-speed transmitter output clock.</p> <p><b>Timing Unit Interval (TUI)</b></p> <p>The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = <math>1/(\text{receiver input clock frequency multiplication factor}) = t_c/w</math>)</p>
	$t_{FALL}$	Signal high-to-low transition time (80-20%)
	$t_{INCCJ}$	Cycle-to-cycle jitter tolerance on the PLL clock input.
	$t_{OUTPJ\_IO}$	Period jitter on the general purpose I/O driven by a PLL.
	$t_{OUTPJ\_DC}$	Period jitter on the dedicated clock output driven by a PLL.
	$t_{RISE}$	Signal low-to-high transition time (20-80%)
U	—	—

**Table 60. Glossary (Part 4 of 4)**

Letter	Subject	Definitions
<b>V</b>	<b>V<sub>CM(DC)</sub></b>	DC common mode input voltage.
	<b>V<sub>ICM</sub></b>	Input common mode voltage—The common mode of the differential signal at the receiver.
	<b>V<sub>ID</sub></b>	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	<b>V<sub>DIF(AC)</sub></b>	AC differential input voltage—Minimum AC input differential voltage required for switching.
	<b>V<sub>DIF(DC)</sub></b>	DC differential input voltage— Minimum DC input differential voltage required for switching.
	<b>V<sub>IH</sub></b>	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	<b>V<sub>IH(AC)</sub></b>	High-level AC input voltage
	<b>V<sub>IH(DC)</sub></b>	High-level DC input voltage
	<b>V<sub>IL</sub></b>	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	<b>V<sub>IL(AC)</sub></b>	Low-level AC input voltage
	<b>V<sub>IL(DC)</sub></b>	Low-level DC input voltage
	<b>V<sub>OCM</sub></b>	Output common mode voltage—The common mode of the differential signal at the transmitter.
	<b>V<sub>OD</sub></b>	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	<b>V<sub>SWING</sub></b>	Differential input voltage
	<b>V<sub>X</sub></b>	Input differential cross point voltage
	<b>V<sub>OX</sub></b>	Output differential cross point voltage
<b>W</b>	<b>W</b>	High-speed I/O block—clock boost factor
<b>X</b>	—	—
<b>Y</b>		
<b>Z</b>		

**Table 61. Document Revision History (Part 3 of 3)**

Date	Version	Changes
May 2013	2.7	<ul style="list-style-type: none"> <li>■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 60</li> <li>■ Added Table 24, Table 48</li> <li>■ Updated Figure 9, Figure 10, Figure 11, Figure 12</li> </ul>
February 2013	2.6	<ul style="list-style-type: none"> <li>■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 35, Table 46</li> <li>■ Updated “Maximum Allowed Overshoot and Undershoot Voltage”</li> </ul>
December 2012	2.5	<ul style="list-style-type: none"> <li>■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 27, Table 30, Table 32, Table 35</li> <li>■ Added Table 33</li> <li>■ Added “Fast Passive Parallel Configuration Timing”</li> <li>■ Added “Active Serial Configuration Timing”</li> <li>■ Added “Passive Serial Configuration Timing”</li> <li>■ Added “Remote System Upgrades”</li> <li>■ Added “User Watchdog Internal Circuitry Timing Specification”</li> <li>■ Added “Initialization”</li> <li>■ Added “Raw Binary File Size”</li> </ul>
June 2012	2.4	<ul style="list-style-type: none"> <li>■ Added Figure 1, Figure 2, and Figure 3.</li> <li>■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 27, Table 29, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 41, Table 43, Table 56, and Table 59.</li> <li>■ Various edits throughout to fix bugs.</li> <li>■ Changed title of document to <i>Stratix V Device Datasheet</i>.</li> <li>■ Removed document from the Stratix V handbook and made it a separate document.</li> </ul>
February 2012	2.3	<ul style="list-style-type: none"> <li>■ Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.</li> </ul>
December 2011	2.2	<ul style="list-style-type: none"> <li>■ Added Table 2–31.</li> <li>■ Updated Table 2–28 and Table 2–34.</li> </ul>
November 2011	2.1	<ul style="list-style-type: none"> <li>■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information about Stratix V GT devices.</li> <li>■ Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.</li> <li>■ Various edits throughout to fix SPRs.</li> </ul>
May 2011	2.0	<ul style="list-style-type: none"> <li>■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2–23, and Table 2–24.</li> <li>■ Updated the “DQ Logic Block and Memory Output Clock Jitter Specifications” title.</li> <li>■ Chapter moved to Volume 1.</li> <li>■ Minor text edits.</li> </ul>
December 2010	1.1	<ul style="list-style-type: none"> <li>■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.</li> <li>■ Converted chapter to the new template.</li> <li>■ Minor text edits.</li> </ul>
July 2010	1.0	Initial release.

